Dynastrip[™] DL7630

- Removes photoresist and post-etch residue from dry metal etch processes
- Dissolves negative photoresist in solder bumping
- For use in single-wafer clean processes

Dynastrip[™] DL88

- Formulated to strip positive photoresist from metals that are sensitive to corrosion
- Dynastrip DL88 is completely water rinsable.
- · Effective for flux residue removal
- Batch spray processing

Dynastrip[™] DL8800

- Designed to strip positive photoresist
- Exceptionally low metal etch rates
- Contains no NMP, DMSO, TMAH, or hydroxylamine

Dynastrip[™] DL9150

- Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
- Improved EH&S footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance

Dynastrip[™] DL9150B

- Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
- Improved EH&S footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance
- Improved Cu compatibility

Dynastrip[™] DL9240

- Green technology for photoresist removal
- Improved EH&S footprint; formulation contains no DMSO and no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); removes negative dry-film resist

FlipStrip™

- · For removal of negative dry-film photoresists that are difficult to remove due to high-temperature reflow process
- Compatible with Cu, Al, and most polyimide (PI)
- Very high loading capacity of photoresist
- Greater than a 72-hour bath life

Dynasolve 219

- For removal of temporary adhesive materials in applications where a better penetrating solvent is required due to a smaller exposed surface area
- Quick dissolving of silicone-based adhesives

Dynasolve FS8320

- Designed specifically for removing flux after solder reflow process
- Cleans rosin, no-clean, and water soluble flux

Dynasolve PI4310

- Proven solution for removal or rework of PI dielectric layers
- · Removes PI through various process stages from coat through post-develop bake process

EH&S (environmental, health, and safety) advantaged—product does not contain any of the following materials:

- Tetramethyl ammonium hydroxide (TMAH)
- Hydroxylamine (HA)
- Dimethylsulfoxide (DMSO)
- N-methylpyrrolidone (NMP)





Photoresist and residue removers

EASTMAN The results of insight

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DYL-011 10/15

Photoresist and residue removers

The family of Dynaloy products cleans a broad range of residue and photoresist from semiconductor wafers. Dynastrip products provide outstanding cleaning and surface preparation utilizing all current cleaning processes such as immersion, spray, and single-wafer.

Dynastrip[™] 7000

- For removal of negative dry-film photoresists
- Cost-effective removal with high loading capacity
- Good heated solution lifetime stability

Dynastrip[™] 7000T

- Cost-effective for removal of both negative dry-film photoresists and positive resists
- Excellent compatibility with most PI layers

Dynastrip[™] 7700 and Dynastrip[™] 7700S

- Successful for dissolving hard to remove thick-negative photoresist in solder bumping processes, including leadfree processes
- Dynastrip™ 7700 is compatible with Cu, Ni, and Sn.

Dynastrip[™] AP1010

- Dynaloy's water-based removal technology, formulated for removal of thick photoresist in an immersion process
- Removes thick-negative dry film or thick-positive or negative spin on photoresist

Dynastrip[™] AP7880-C

- Proven and patented technology for dissolving hardest to remove thick-negative dry-film photoresist in leadfree solder bumping and Cu pillar processes
- $\,^{\circ}$ Effective for removal of post-etch residues created by $\,^{\circ}$ $\,^{\circ}$ plasma ashing after dry etch on vias and metals
- Dynastrip AP7880-C is compatible with Al, Cu, Ni, and Sn.

Dynastrip[™] AP7880-NA and Dynastrip[™] AP7880-NT

- Proven and patented removal technology, formulated for removal of thick photoresist used in advanced packaging and Cu pillar processes
- Removes thick-negative dry film or thick-positive or negative spin on photoresist
- Lower cost version of Dynaloy's premium AP7880-C
- Dynastrip AP7880-NT available in Asia Pacific market
- Dynastrip AP7880-NA available in North American market

Dynastrip[™] AP7880-T

- Effective for dissolving hard to remove thick-negative photoresist in solder bumping processes including Cu pillar and lead-free processes
- High loading capacity results in low process CoO
- Available only in Asia Pacific market

Dynastrip[™] AP7900A

- Formulated to strip thick photoresist in Cu pillar processes
- High loading capacity
- Long heated bath lifetime

Dynastrip[™] AP7900C

- Formulated to strip thick photoresist in Cu pillar processes
- High loading capacity
- Long heated bath lifetime
- Available only in Asia Pacific market

Dynastrip[™] DL3000

- Strips cyclized negative photoresist that has been exposed and processed
- Dynastrip[™] DL3000 is noncorrosive to most metals.
- Contains no phenols or chlorinated hydrocarbons

	Dynastrip™ 7000	Dynastrip™ 7000T	Dynastrip™ 7700/7700S	Dynastrip" AP1010	Dynastrip" AP7880-C	Dynastrip" AP7880-NA/NT	Dynastrip" AP7880-T	Dynastrip™ AP7900A	Dynastrip™ AP7900C	Dynastrip" DL3000	Dynastrip" DL7630	Dynastrip™ DL88	Dynastrip" DL8800	Dynastrip" DL9150	Dynastrip" DL9150B	Dynastrip™ DL9240	FlipStrip™	Dynasolve 219	Dynasolve FS8320	Dynasolve PI4310
Electroplated solder bump—photoresist strip																				
Negative dry-film photoresist	•	•	•	•	•	•	•				•			•	•	•	•			
Negative liquid photoresist	•	•	•	•	•	•	•				•			•	•	•	•			
Positive photoresist								•	•											
Cu Pillar—photoresist strip																				
Negative dry-film photoresist			•	•	•	•	•				•			•	•	•				
Negative liquid photoresist			•	•	•	•	•				•			•	•	•				
Positive photoresist								•	•											
TSV Clean—DRIE post-etch residue removal																				
Post-etch residue					•	•								•	•					
RDL—photoresist removal																				
Positive photoresist								•	•			•	•							
Post-reflow flux removal																				
Flux																			•	
Post-Bosch etch residue removal (DRIE PERR)																				
Post-etch residue					•	•								•	•					
General photoresist removal																				
Positive photoresist		•						•	•			•	•							
Temporary bonding adhesive removal																				
Silicone adhesive																		•		
Passivation rework																				
Polyimide																				•
Photoresist removal																				
Negative cyclized resist										•										
Sustainably advantaged																				
EH&S advantaged				•						•			•	•	•	•		•		
Reduced volume																				